

L9	37	3 and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:18
L10	8	4 and 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 10:54
L11	10	5 and 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:14
L12	0	6 and 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 10:53
L13	133275	("250"/\$7.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:12
L14	92439	("356"/\$7.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:12
L15	112782	("414"/\$7.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:13
L16	42987	("700"/\$6.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:14

L17	27	1 and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:19
L18	203	1 and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:19
L19	17	13 and 18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:20
L20	44	14 and 18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:21
L21	6	15 and 18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:23
L22	18	16 and 18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:23

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1067	(selected or selecting or select or assign\$6) near6 ((wafer) near3 (group\$2 or number\$2))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 10:13
L2	65041	((wafer\$2) near16 (semiconductor or integrat\$3)) near23 (pattern\$2 or circuit\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 10:15
L3	26322	(divide or dividing or clasifying or classify or defining or define) near18 ((chip\$2 or wafer\$2 or pattern\$2) near12 (region\$2 or group\$2 or areas))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 10:18
L4	24867	((inspect\$6 or measur\$6) near26 (pattern\$2 or wafer\$2 or chip\$2)) near32 (semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 10:20
L5	8519	((inspect\$6 or measur\$6) near6 (pattern\$2)) near32 (semiconductor or wafer\$2 or reticle\$2)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 10:21
L6	7413	(pattern\$2) and (semiconductor) and (inspect\$6 or detect\$6 or measur\$6) and (group\$2 or region\$2) and (control or controlling) and (select\$6) and (lattice\$3) and (point)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 10:24
L7	1	(measur\$6 near3 schedule\$2) and (measur\$6 near3 point\$2) and ((wafer\$2) near3 (group\$2 or number\$2)) and (lattice) and (regions or areas) and (select or selecting) and (dividing) and (assign\$6 or classif\$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 10:53
L8	462	1 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/30 12:11